



Title of Change:	Contact mask change for TIGBT technology mask sets.		
Proposed First Ship date:	13 May 2020 or earlier if approved by customer		
Contact Information:	Contact your local ON Semiconductor Sales Office or SayMeng.Lim@onsemi.com		
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>		
Marking of Parts/ Traceability of Change:	N/A		
Change Category:	Wafer Fab Change		
Change Sub-Category(s):	Contact mask change		
Sites Affected:			
ON Semiconductor Sites	External Foundry/Subcon Sites		
ON Semiconductor Niigata, Japan	None		
ON Semiconductor Roznov, Czech Republic			
Description and Purpose:			
This IPCN is to inform that, ON Semiconductor is resizing gate pad contacts from 1.3x1.3um to 1.5x1.5um for all the devices listed in this IPCN. This change is an effort of a continuous improvement to the robustness of the wafer process allowing better gate pad contact, while maintaining the current performances of the affected parts.			
	Before Change Description	After Change Description	
Gate pad contact	1.3um x 1.3um	1.5um x 1.5um	
There is no product marking change as a result of this change.			
Qualification Plan:			
QV DEVICE NAME: NGTB40N120FL2WG			
PACKAGE: TO-247			
Test	Specification	Condition	Interval
TC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc
Estimated date for qualification completion: 9 March 2020			



List of Affected Parts:

*Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.*

Part Number	Qualification Vehicle
NGTB45N60S2WG	NGTB40N120FL2WG
NGTB40N65IHL2WG	NGTB40N120FL2WG
NGTB30N65IHL2WG	NGTB40N120FL2WG
NGTB40N60FL2WG	NGTB40N120FL2WG
NGTB40N65FL2WG	NGTB40N120FL2WG
NGTB35N65FL2WG	NGTB40N120FL2WG
NGTB35N60FL2WG	NGTB40N120FL2WG
NGTB50N65FL2WG	NGTB40N120FL2WG
NGTB50N60S1WG	NGTB40N120FL2WG
NGTB50N65FL2WAG	NGTB40N120FL2WG
NGTB30N120SWG	NGTB40N120FL2WG
NGTB25N120FL2WG	NGTB40N120FL2WG
NGTG40N120FL2WG	NGTB40N120FL2WG
NGTB50N120FL2WG	NGTB40N120FL2WG
NGTB40N120FL2WG	NGTB40N120FL2WG
NGTG25N120FL2WG	NGTB40N120FL2WG
NGTB15N135IHRWG	NGTB40N120FL2WG
NGTG15N120FL2WG	NGTB40N120FL2WG
NGTB15N120IHWG	NGTB40N120FL2WG
NGTB15N120FL2WG	NGTB40N120FL2WG
NGTB30N120L2WG	NGTB40N120FL2WG



Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NGTB30N120L2WG		NGTB40N120FL2WG		
NGTB15N120FL2WG		NGTB40N120FL2WG		
NGTB15N120IHWG		NGTB40N120FL2WG		
NGTG25N120FL2WG		NGTB40N120FL2WG		
NGTB40N120FL2WG		NGTB40N120FL2WG		
NGTB50N120FL2WG		NGTB40N120FL2WG		
NGTG40N120FL2WG		NGTB40N120FL2WG		
NGTB25N120FL2WG		NGTB40N120FL2WG		
NGTB35N60FL2WG		NGTB40N120FL2WG		
NGTB35N65FL2WG		NGTB40N120FL2WG		
NGTB40N65FL2WG		NGTB40N120FL2WG		
NGTB40N60FL2WG		NGTB40N120FL2WG		
NGTB40N65IHL2WG		NGTB40N120FL2WG		
NGTB45N60S2WG		NGTB40N120FL2WG		